

N and P-Channel Enhancement Mode Power MOSFET

Description

The MJ30NP07S uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

General Features

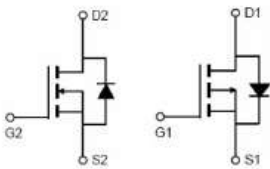
N-Channel

- ◆ $V_{DS}=30V, I_D=6.5A$
 $R_{DS(ON)}<24m\Omega @ V_{GS}=10V$
 $R_{DS(ON)}<37m\Omega @ V_{GS}=4.5V$

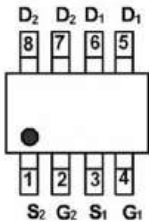
P-Channel

- ◆ $V_{DS}=-30V, I_D=-7A$
 $R_{DS(ON)}<32m\Omega @ V_{GS}=-10V$
 $R_{DS(ON)}<70m\Omega @ V_{GS}=-4.5V$

- ◆ High power and current handing capability
- ◆ Lead free product is acquired
- ◆ Surface mount package



N-channel P-channel
Schematic diagram



Marking and pin assignment



SOP-8 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJ30NP07S	MJ30NP07S	SOP-8	Ø330mm	12mm	4000 units

Absolute Maximum Ratings ($T_A=25^{\circ}C$ unless otherwise noted)

Parameter		Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage		V_{DS}	30	-30	V
Gate-Source Voltage		V_{GS}	±20	±20	V
Continuous Drain Current	$T_A=25^{\circ}C$	I_D	6.5	-7	A
	$T_A=70^{\circ}C$	I_D	5.4	-5.8	A
Pulsed Drain Current ^(Note 1)		I_{DM}	30	-30	A
Maximum Power Dissipation	$T_A=25^{\circ}C$	P_D	2.0	2.0	W
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55 To 150	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient ^(Note 2)	$R_{\theta JA}$	N-Ch	62.5	°C/W
Thermal Resistance, Junction-to-Ambient ^(Note 2)	$R_{\theta JA}$	P-Ch	62.5	°C/W

N-CH Electrical Characteristics (T_A=25℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	30	33	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{DS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	1	1.6	3	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =6A	-	19	24	mΩ
		V _{GS} =4.5V, I _D =6A	-	26	37	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V,I _D =6A	15	-	-	S
Dynamic Characteristics (Note 4)						
Input Capacitance	C _{iss}	V _{DS} =15V,V _{GS} =0V F=1.0MHz	-	485.8	-	PF
Output Capacitance	C _{Oss}		-	65.2	-	PF
Reverse Transfer Capacitance	C _{rss}		-	54	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =15V, R _L =2.5Ω V _{GS} =10V,R _{GEN} =3Ω	-	4.0	-	nS
Turn-on Rise Time	t _r		-	2.0	-	nS
Turn-Off Delay Time	t _{d(off)}		-	14.0	-	nS
Turn-Off Fall Time	t _f		-	3.0	-	nS
Total Gate Charge	Q _g	V _{DS} =15V,I _D =6A V _{GS} =10V	-	12.6	-	nC
Gate-Source Charge	Q _{gs}		-	1.9	-	nC
Gate-Drain Charge	Q _{gd}		-	2.6	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =6A	-	0.8	1.2	V

P-CH Electrical Characteristics (TA=25℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-30	-33	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-30V,V _{GS} =0V	-	-	-1	μA
Gate-Body Leakage Current	I _{GSS}	V _{DS} =±20V,V _{GS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =-250μA	-1.3	-1.65	-2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-6.5A	-	28	32	mΩ
		V _{GS} =-4.5V, I _D =-6.5A	-	49	70	mΩ
Forward Transconductance	g _{FS}	V _{DS} =-5V,I _D =-6.5A	10	-	-	S
Dynamic Characteristics (Note 4)						
Input Capacitance	C _{iss}	V _{DS} =-15V,V _{GS} =0V F=1.0MHz	-	691.9	-	PF
Output Capacitance	C _{OSS}		-	113.7	-	PF
Reverse Transfer Capacitance	C _{rss}		-	109.4	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =-15V, R _L =2.3Ω V _{GS} =-10V,R _{GEN} =6Ω	-	7.5	-	nS
Turn-on Rise Time	t _r		-	5.5	-	nS
Turn-Off Delay Time	t _{d(off)}		-	19	-	nS
Turn-Off Fall Time	t _f		-	7	-	nS
Total Gate Charge	Q _g	V _{DS} =-15V,I _D =-6.5A V _{GS} =-10V	-	16.3	-	nC
Gate-Source Charge	Q _{gs}		-	2.2	-	nC
Gate-Drain Charge	Q _{gd}		-	4.1	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-6.5A	-	-	-1.2	V

Notes:

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Surface Mounted on FR4 Board, t ≤ 10 sec.
- ③ Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
- ④ Guaranteed by design, not subject to production

N- Channel Typical Electrical and Thermal Characteristics (Curves)

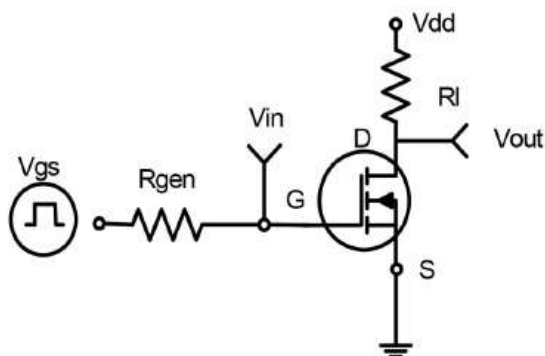


Figure 1 Switching Test Circuit

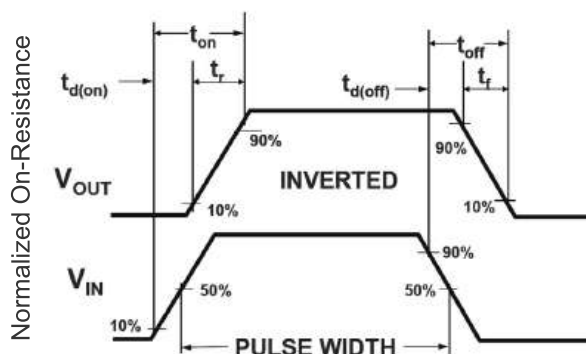


Figure 2 Switching Waveforms

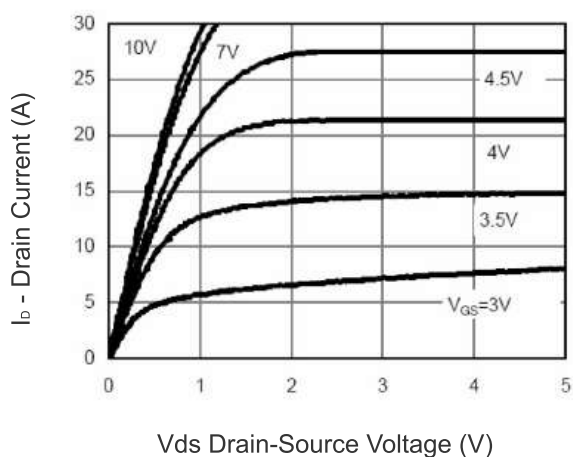


Figure 3 Output Characteristics

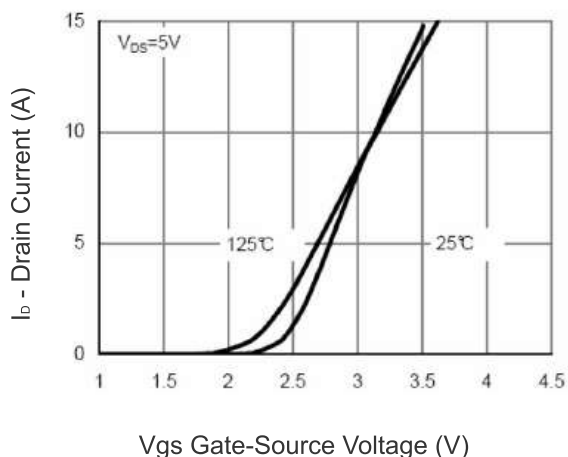


Figure 4 Transfer Characteristics

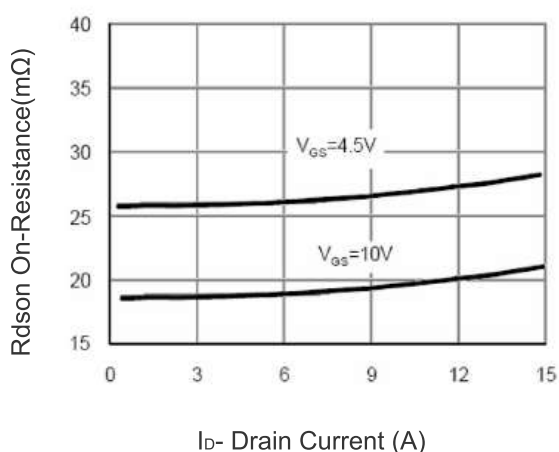


Figure 5 Drain-Source On-Resistance

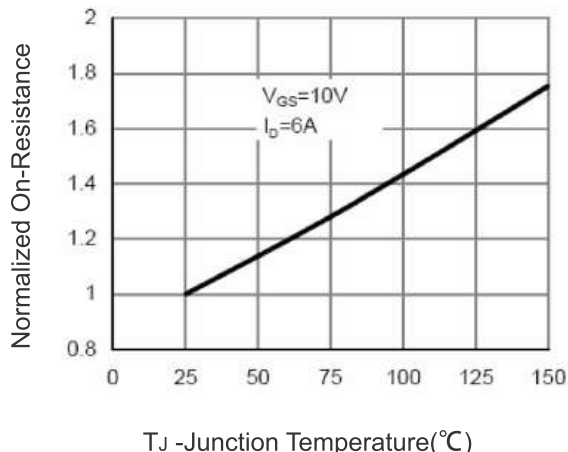
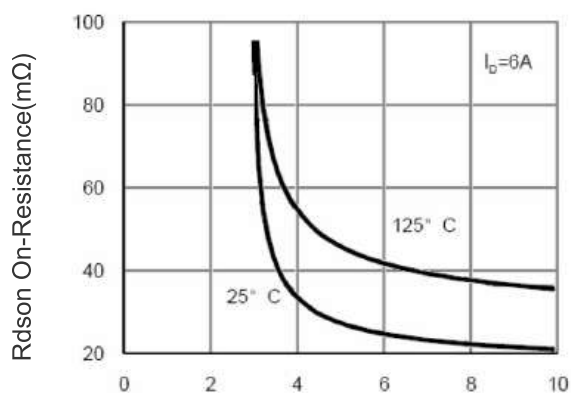
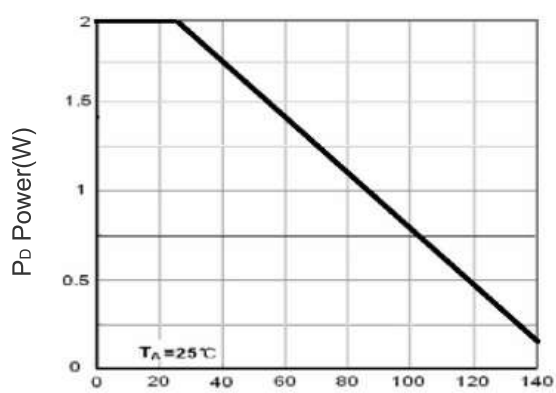


Figure 6 Drain-Source On-Resistance



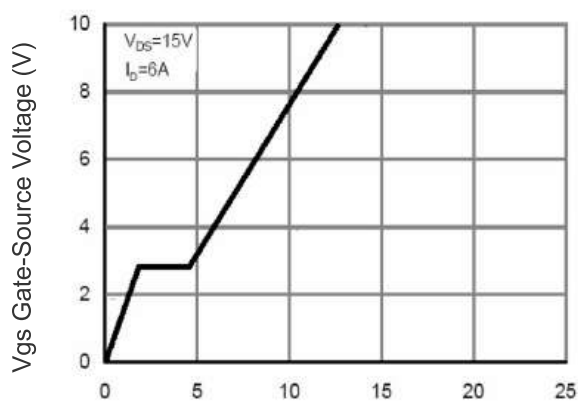
Vgs Gate-Source Voltage (V)

Figure7 Rdson vs Vgs



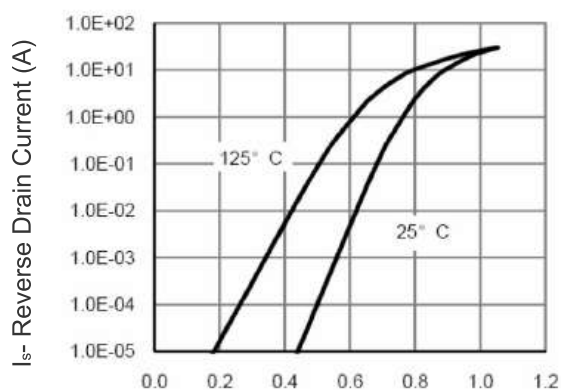
TJ -Junction Temperature(°C)

Figure 8 Power Dissipation



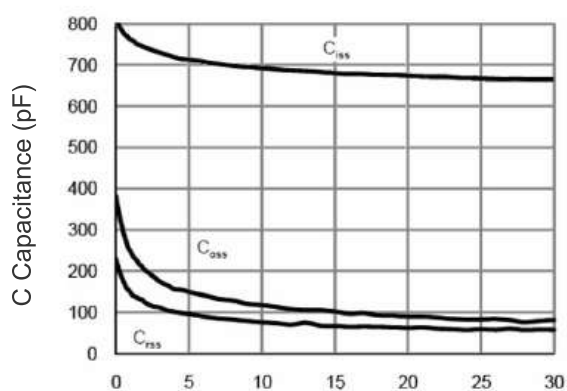
Qg Gate Charge (nC)

Figure 9 Gate Charge



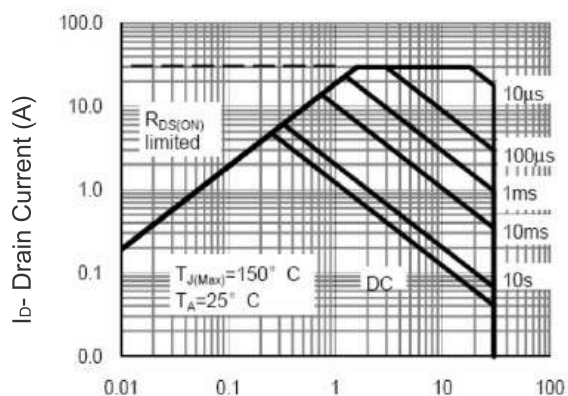
Vds Drain-Source Voltage (V)

Figure 10 Source- Drain Diode Forward



Vds Drain-Source Voltage (V)

Figure 11 Capacitance vs Vds



Vds Drain-Source Voltage (V)

Figure 12 Safe Operation Area

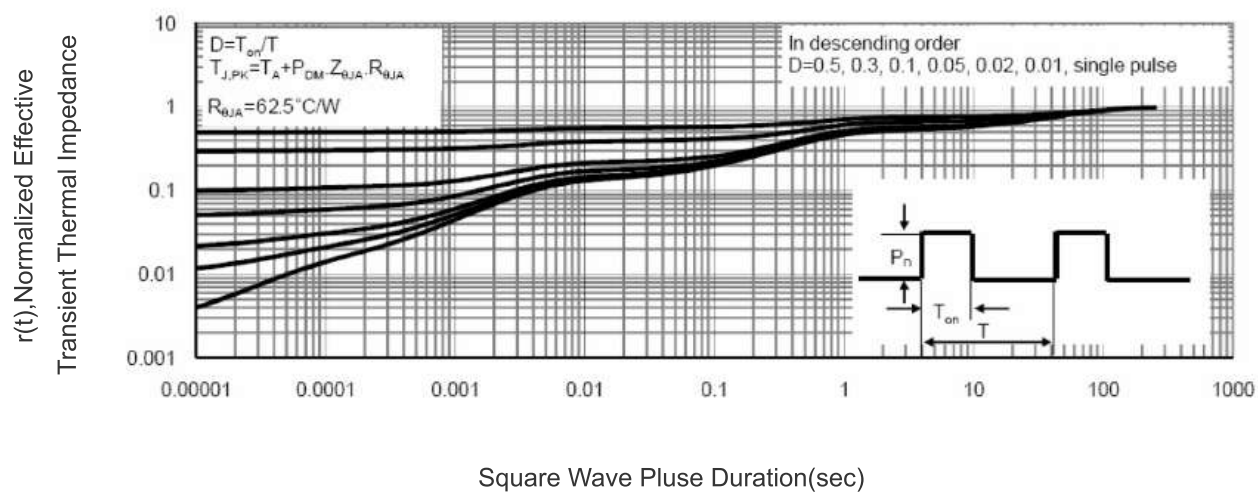
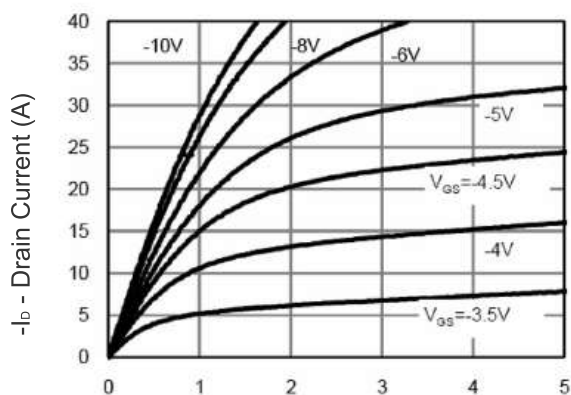


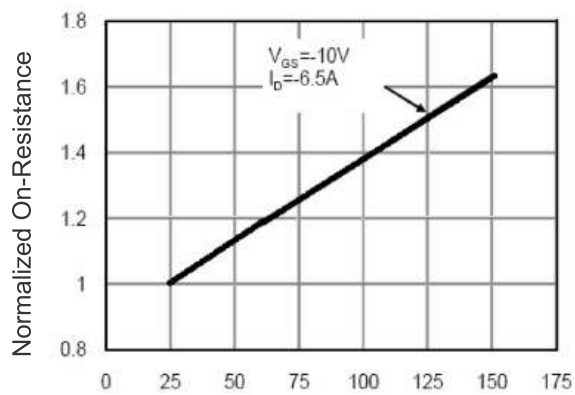
Figure 13 Normalized Maximum Transient Thermal Impedance

P- Channel Typical Electrical and Thermal Characteristics (Curves)



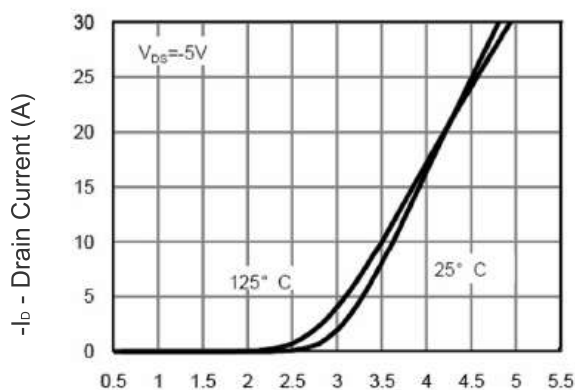
-V_{DS} Drain-Source Voltage (V)

Figure 1 Output Characteristics



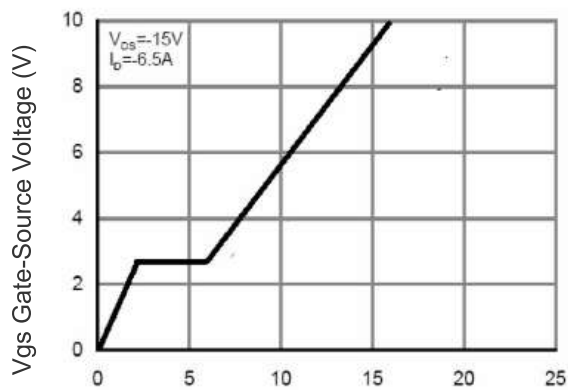
T_J -Junction Temperature(°C)

Figure 4 R_{DS(on)}-Junction Temperature



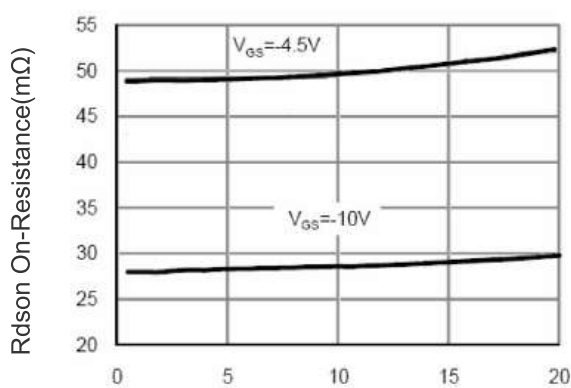
-V_{GS} Gate-Source Voltage (V)

Figure 2 Transfer Characteristics



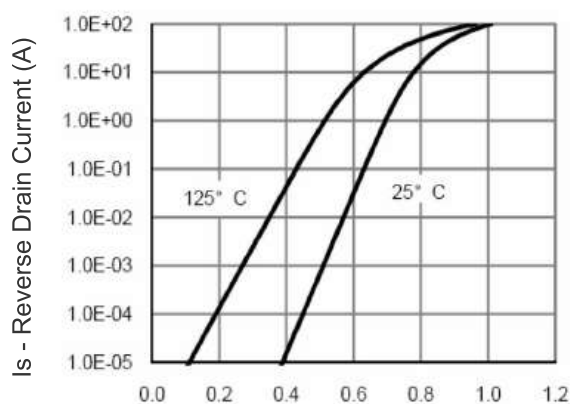
Q_g Gate Charge (nC)

Figure 5 Gate Charge



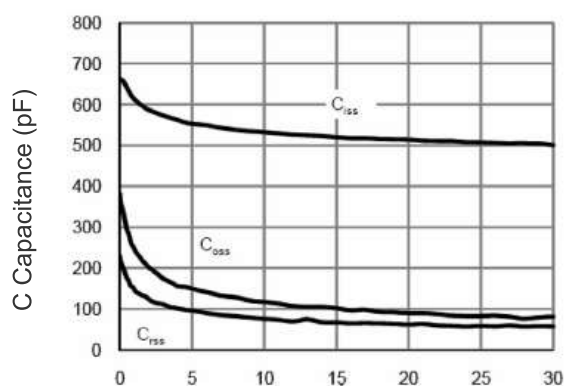
I_D- Drain Current (A)

Figure 3 R_{DS(on)}- Drain Current

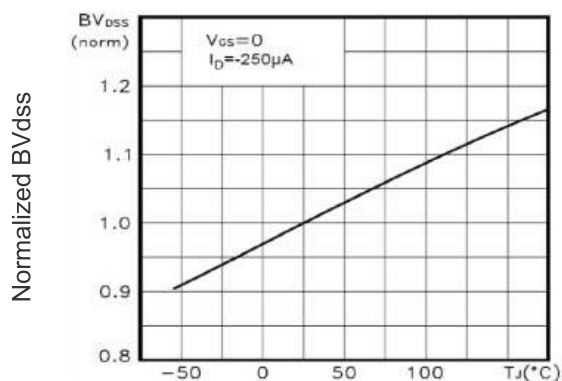


V_{SD} Source-Drain Voltage (V)

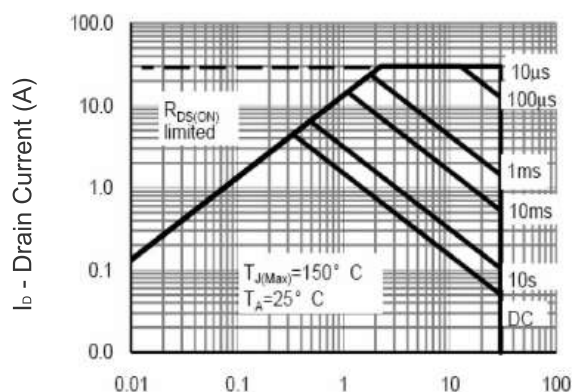
Figure 6 Source- Drain Diode Forward



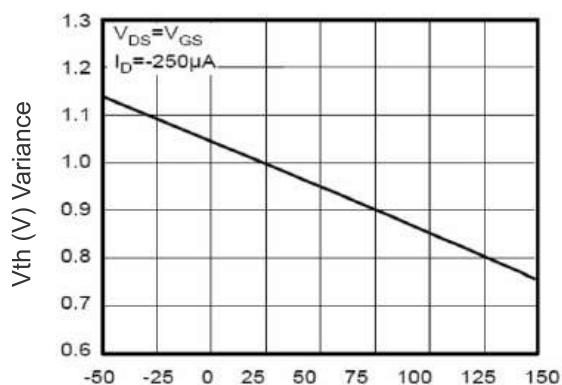
Vds Drain-Source Voltage (V)
Figure 7 Capacitance vs Vds



TJ -Junction Temperature(°C)
Figure 9 BVDSS vs Junction Temperature



Vds Drain-Source Voltage (V)
Figure 8 Safe Operation Area



TJ -Junction Temperature(°C)
Figure 10 VGS(th) vs Junction Temperature

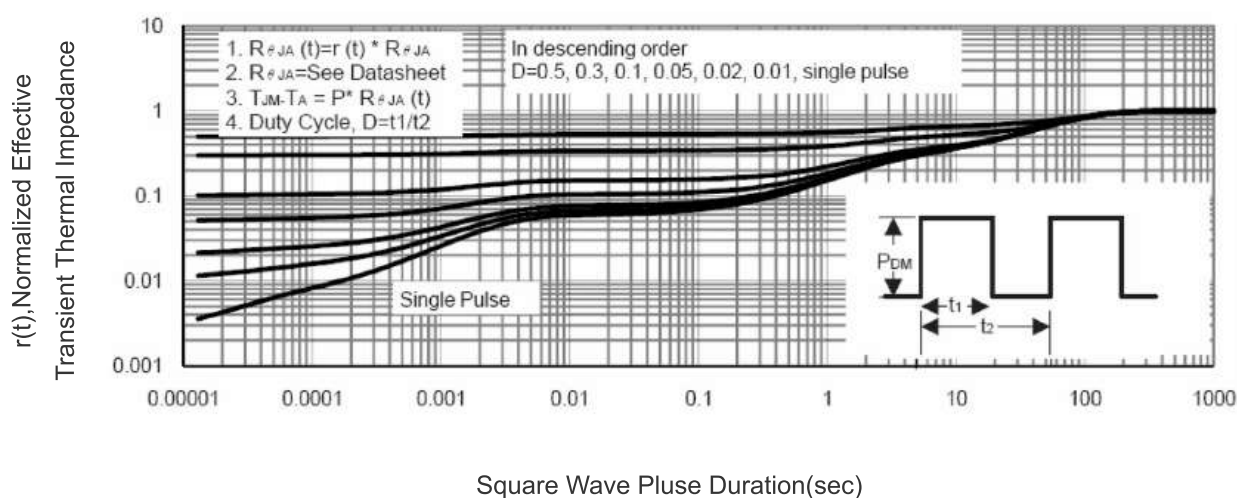
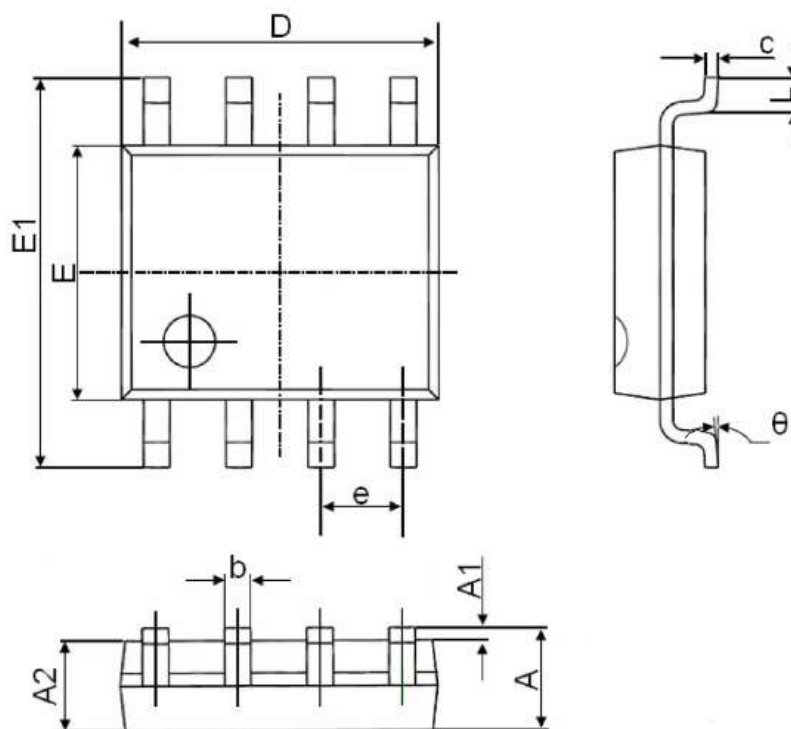


Figure 11 Normalized Maximum Transient Thermal Impedance

SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

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